



ASE Receives Supplier of the Year Award from Broadcom

Santa Clara, California, February 20, 2008 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world’s largest semiconductor packaging and test company, announced today that it has received a 2007 Supplier of the Year award from Broadcom Corporation. Broadcom, a global leader in semiconductors for wired and wireless communications, selected ASE for demonstrating exceptional technology, quality, service, and delivery in its contribution to Broadcom’s packaging and test solutions.

ASE provides Broadcom with full turnkey services, encompassing bumping, WLCSP, BGA/Leadframe packaging, wafer probe, and final test solutions. With facilities strategically located in Taiwan, China, and Singapore, ASE offers compelling capacity and manufacturing advantages, complemented by expert local support teams dedicated to the alignment of package technology roadmaps with qualified packaging technologies. As a result, ASE received top rating from Broadcom over four consecutive quarters in 2007.

“Broadcom's ongoing commitment to working together with key partners, such as ASE, helps us meet the high standards for quality, productivity and efficiency that our customers deserve and our competitive business environment demands,” said Vahid Manian, Senior Vice President, Global Manufacturing Operations. “Over the past year, ASE has consistently demonstrated its dedication and expertise so we are pleased to recognize these efforts with this prestigious award.”

“ASE is honored to accept this accolade from a world-class company such as Broadcom, who we provide the advanced technologies and turn-key services that truly makes ASE a one-stop partner,” said Dr Tien Wu, COO, ASE Group. “This award is a reflection of our unwavering focus and commitment to customer success, the collaborative nature of our customer relationships, and our track record of delivering beyond the expectations of our customers around the world.”

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry’s ever growing needs for faster, smaller and higher performance chips, the Group

develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$3.1 billion in 2007 and employs over 28,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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